



Media Release

(all figures in US\$ unless otherwise stated)

Qimonda and UTAC Establish and Extend Joint Technology Co-operation in Ultra-Thin Die and Multi-Chip Packaging

Singapore, 25 September, 2006 – Singapore Exchange-listed United Test and Assembly Center Ltd (“UTAC” – SGX:UTAC), a leading independent global provider of semiconductor assembly and test services, today announced it had successfully completed its first joint research and development (“R&D”) collaboration with Qimonda AG (“Qimonda”) on ultra-thin large die-stacking process development. Based on the success of this collaborative effort, both companies have agreed to extend the R&D initiatives by a further eighteen months and to encompass advanced stacking and Flip Chip technology.

Munich-headquartered Qimonda, the new memory company carved out from Infineon Technologies AG on 1 May 2006, is a leading global producer of DRAM memory products. Qimonda has access to manufacturing sites on three continents. With a historical emphasis on PC and server products, the company is now focusing on products for graphics, mobile and consumer applications.

UTAC’s joint-development efforts with Qimonda, which started about eighteen months ago, has succeeded in providing innovative multi-chip package solutions with high density of functionality and high performance in reliability and yielded a “toolbox” with a set of design rules, materials and processes that enable fast turnaround for the design and manufacture of innovative multi-chip packages with multiple stacking of very thin large-die semiconductor chips such as high density DRAM and flash memory with the flexibility to handle both center or peripheral bond pads. The toolbox has the flexibility to handle up to four large dies and three spacers (“4+3”) and yet maintain a thickness of no more than 1.4 mm and the possibility of stacking four active chips in a package with 1.0 mm thickness.



The successful joint development effort has resulted in UTAC Singapore becoming qualified as part of Qimonda's manufacturing cluster in the production of multiple die stack packages for support of Qimonda's ongoing and future multi-chip package product requirements.

"We are thrilled to be a key partner of Qimonda, with its well reputed technology base, as it establishes itself as a leading provider of innovative memory solutions to the market," said Ms June Chia, Group Executive Vice President of UTAC.

"UTAC has over the past few quarters enhanced its capabilities in testing and assembling flash memory and DRAM modules and we are pleased to be able to further extend our capability to support Qimonda on multi-chip packages going forward," added Dr Anthony Sun, Group Vice President of Packaging and Assembly Technology of UTAC.

"UTAC has been a key manufacturing partner for us over the years and we are happy to expand this relationship into an extended joint R&D program. This new technology pool is an important competitive advantage as it enables us to respond much faster, with more flexibility to customer requests," said Diether Sommer, Senior Director, Packaging Technology, responsible for Back-end Technology at Qimonda.



About UTAC

United Test and Assembly Center Ltd (“UTAC”, SGX-ST: UTAC) is a leading independent provider of semiconductor assembly and testing services for a broad range of integrated circuits including memory, mixed-signal, logic and radio-frequency ICs. The company offers a full range of package and test development, engineering and manufacturing services and solutions to a worldwide customer base, comprising leading integrated device manufacturers (“IDMs”), fabless companies and wafer foundries. UTAC operates manufacturing facilities in Singapore, Thailand, Taiwan and China, in addition to its global network of sales offices in the United States, Europe, Japan, Korea, China and Singapore. More information on the company can be found at www.utacgroup.com.



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